



## Materials Declaration Form


<b>IPC Form Type *</b>	<b>1752 Distribute</b>	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	<b>Material Info Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2018-06-07</b>
<b>Company Unique ID</b>	<b>NL 008751171B01</b>		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>MDG MD CHAMPION</b>	<b>Representative Title</b>	<b>MDG MD CHAMPION</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

Uncertainty Statement	
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Legal Statement	
<b>Supplier Acceptance *</b>	<b>true</b>
<b>Legal Declaration *</b>	<b>Standard</b>
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F072C8Y7TR	H33D*448CCCY	A	9989	2018-06-07
	Amount	UoM	Unit type	ST ECOPACK Grade
	6.32	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Solder ball SACN125 0.23mm	NAC	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
WL CSP	Not Applicable	Nbr of instances	No lead	
Comment	Package : A01N WL CSP 25L P 0.4 MM DIE 444 8539860			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	H33D*448CCY				8000000.0	999865.5
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	4.966	mg	supplier	die	Silicon (Si)	7440-21-3		4.747	mg	955900	750528
				supplier	metallization	Aluminium (Al)	7429-90-5		0.015	mg	3021	2372
				supplier	metallization	Copper (Cu)	7440-50-8		0.074	mg	14901	11700
				supplier	metallization	Cobalt (Co)	7440-48-4		0.014	mg	2819	2213
				supplier	metallization	Titanium (Ti)	7440-32-6		0.004	mg	805	632
				supplier	metallization	Tungsten (W)	7440-33-7		0.008	mg	1611	1265
				supplier	Passivation	Silicon Nitride	12033-89-5		0.010	mg	2014	1581
				supplier	Passivation	Silicon Oxide	7631-86-9		0.094	mg	18929	14862
RDL-Ti Target	M-011 Other inorganic materials	0.001	mg	Supplier	Metals	Titanium	7440-32-6		0.001	mg	1000000	182
RDL-Cu Target	M-011 Other inorganic materials	0.005	mg	Supplier	Metals	Copper	7440-50-8		0.005	mg	1000000	721
RDL-Cu Anode	M-011 Other inorganic materials	0.091	mg	Supplier	Metals	Copper	7440-50-8		0.091	mg	1000000	14448
UBM-Ti Target	M-011 Other inorganic materials	0.000	mg	Supplier	Metals	Titanium	7440-32-6		0.000	mg	1000000	74
UBM-Cu Target	M-011 Other inorganic materials	0.002	mg	Supplier	Metals	Copper	7440-50-8		0.002	mg	1000000	294
UBM-Cu Anode	M-011 Other inorganic materials	0.080	mg	Supplier	Metals	Copper	7440-50-8		0.080	mg	1000000	12656
SOLDER BALLS SACN125 0.23mm	Solder	1.179	mg	Supplier	Metals	Tin	7440-31-5		1.146	mg	972569	181226
				Supplier	Metals	Silver	7440-22-4		0.014	mg	11970	2230
				Supplier	Metals	Copper	7440-50-8		0.018	mg	15461	2881